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December 20, 2001

Commissioner for Patents  
Washington, D.C. 20231**Attorney Docket No. DKC 1800****RE: New Patent Application of LEE ET AL**

Enclosed herewith are the application papers for a patent in the name(s) of Shi-Choon Lee and Byung-Sun Kim entitled: "GLASS FIBER REINFORCED STYRENIC THERMOPLASTIC COMPOSITES CONTAINING AN AMINOSILANE COUPLING AGENT".

Enclosed are:

Specification	16 pages
Claims 1-18	
Abstract	
Declaration	
Application Data Sheet	3 pages
Credit Card Payment Form for Filing Fee	
✓ Assignment	
Recordation Cover Sheet	
Credit Card Payment Form for Recordation of Assignment	

Filing Fee Calculation:

		Number Filed	Number extra			
Basic Filing Fee					\$	740
Total Claims:	18	- 20	0	x \$18	0	
Independent claims:	4	- 3	1	x \$84	84	
Multiple dependent claims:				\$270	0	
SUBTRACT ONE-HALF FOR SMALL ENTITY					0	
TOTAL FILING FEE					\$	824

[illegible]

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Respectfully submitted,

2 Page

(Reg. No. 31,720)

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